ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SOIC 8-LEAD (DY)					
Stress	**Sample Size**	**Device Hr./Cyc**	**Condition**	**Total Fails**	**Fail Percentage**
BOND INT	3,240	1,566,400	200 °C + N2	0	0.00
DIE SHEAR	20	1,600	MIL–STD–750	0	0.00
HAST	18,534	1,898,520	130 °C, 85 % RH	0	0.00
HIGH TEMP STORAGE	246	41,656	200 °C	0	0.00
Power Cycle	725	509,160	DELTA Tj = 100	0	0.00
Pressure Pot	29,551	2,958,088	121°, 15 PSIG	0	0.00
Solder DUNK	4,087	12,561	260 °C, 10 SEC	0	0.00
Solderability	2,475	20,365	883 M2003	0	0.00
Temp Cycle	32,334	16,007,004	–65 °C – 150 °C	0	0.00
Thermal Shock	5,350	535,000	–60 °C – 150 °C	0	0.00